

High voltage fast-switching NPN Power Transistor

General features

- NPN Transistor
- High voltage capability
- Low spread of dynamic parameters
- Minimum lot-to-lot spread for reliable operation
- Very high switching speed
- In compliance with the 2002/93/EC European Directive

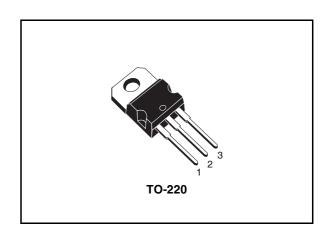
Description

The device is manufactured using high voltage Multi-Epitaxial Planar technology for high switching speeds and medium voltage capability.

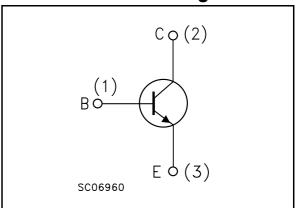
It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

Applications

- Electronic ballast for fluorescent lighting
- Dedicated for PFC solution in HF ballast halfbridge voltage fed



Internal schematic diagram



Order codes

Part Number	Marking	Package	Packing
BUL704	BUL704	TO-220	Tube

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BUL704 Electrical ratings

1 Electrical ratings

Table 1. Absolute maximum rating

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage (V _{BE} = 0)	700	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	400	V
V _{EBO}	Emitter-base voltage (I _C = 0)	10	V
I _C	Collector current	4	Α
I _{CM}	Collector peak current (t _P < 5ms)	8	Α
I _B	Base current	2	Α
I _{BM}	Base peak current (t _P < 5ms)	4	Α
P _{tot}	Total dissipation at T _c = 25°C	70	W
T _{stg}	Storage temperature	-65 to 150	°C
TJ	Max. operating junction temperature	150	°C

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	1.78	°C/W
R _{thj-amb}	Thermal resistance junction-amb max	62.5	°C/W

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Electrical characteristics BUL704

2 Electrical characteristics

 $(T_{case} = 25^{\circ}C \text{ unless otherwise specified})$

Table 3. Electrical characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{CES}	Collector cut-off current (V _{BE} =-1.5V)	V _{CE} =700V V _{CE} =700V T _j =125°C			100 500	μ Α μ Α
I _{CEO}	Collector cut-off current (I _B =0)	V _{CE} =400V			250	μА
V _{EBO}	Emitter-base voltage (I _C = 0)	I _E =10mA	10			V
V _{CEO(sus)} (1)	Collector-emitter sustaining voltage (I _B = 0)	I _C =100mA L =25mH	400			V
V _{CE(sat)} (1)	Collector-emitter saturation voltage	I _C =1A I _B =0.2A I _C =2.5A I _B =0.5A			0.5 0.8	V V
V _{BE(sat)} (1)	Base-emitter saturation voltage	I _C =1A I _B =0.2A I _C =2.5A I _B =0.5A			1.1	V
h _{FE}	DC current gain	I _C =10mA V _{CE} =5V I _C =2A V _{CE} =5V	10 14		28	
t _s	Resistive load Storage time Fall time	$V_{CC} = 125V$ $I_{C} = 2A$ $I_{B1} = -I_{B2} = 0.4A$ $I_{p} = 30\mu s$ (see fig.12)	1.5	0.2	3 0.4	μs μs
t _s	Inductive load Storage time Fall time	$\begin{split} & I_{\text{C}} = \!\! 2\text{A} & I_{\text{B1}} = \!\! 0.4\text{A} \\ & V_{\text{BE(off)}} = \!\! -5\text{V} & R_{\text{BB}} = \!\! 0\Omega \\ & V_{\text{clamp}} \! = \!\! 200\text{V} & \text{(see fig.13)} \end{split}$		0.6 0.1	1 0.2	μs μs

Note (1) Pulsed duration = 300 μ s, duty cycle \leq 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

Figure 2. Derating Curve

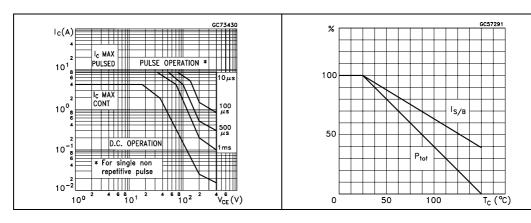


Figure 3. DC current gain

Figure 4. DC current gain

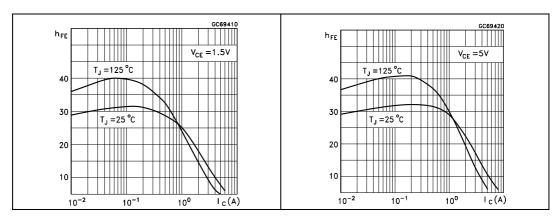
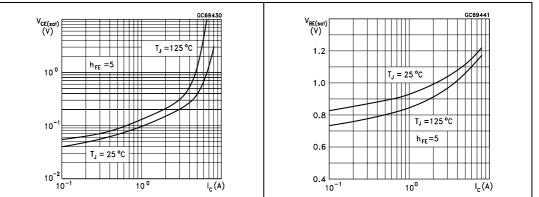


Figure 5. Collector-emitter saturation voltage

Figure 6. Base-emitter saturation voltage



Electrical characteristics BUL704

Figure 7. Inductive load fall time

Figure 8. Inductive load storage time

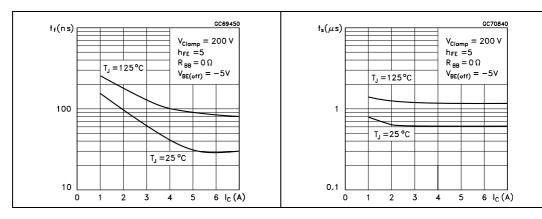


Figure 9. Resistive load fall time

Figure 10. Resistive load storage time

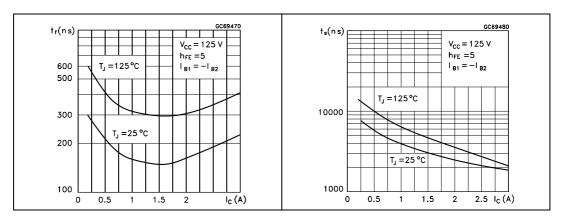
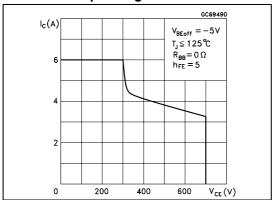


Figure 11. Reverse biased safe operating area



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2.2 Test circuits

Figure 12. Resistive load switching test circuit

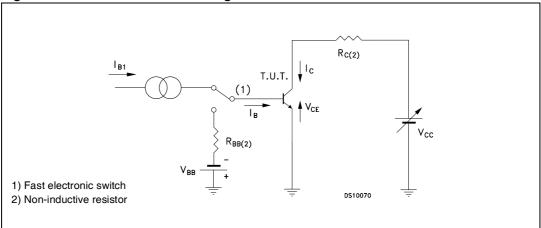
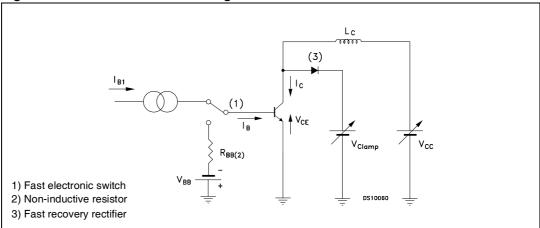


Figure 13. Inductive load switching test circuit

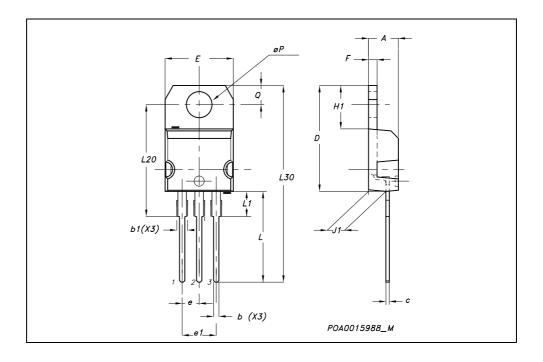


3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-220 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
С	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
Е	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øΡ	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



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Revision history BUL704

4 Revision history

Table 4. Revision history

Date	Revision	Changes
30-May-2006	1	Initial release.

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